



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Daniel C. Wang

Application No.: 09/737,642

Filed: December 14, 2000

Title: METAL-TO-METAL ANTIFUSE  
STRUCTURE AND FABRICATION  
METHOD

Group Art Unit:  
2815

Examiner:  
Jose R. Diaz

Attorney Docket No.: ACT-311

#8/B

Amend

J. McInnis  
12/27/02

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail, in an envelope addressed to Director of Patents, Washington, D.C. 20231 on December 11, 2002, Signed

Paul McCoy

RESPONSE TO OFFICE ACTION

Director of Patents  
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed on September 11, 2002, Applicant respectfully requests reconsideration of the present rejections and reexamination of the present application in view of the following remarks.

RECEIVED  
DEC 18 2002  
TC 2800 MAIL ROOM

AMENDMENTS

In the Claims

Kindly amend claims 1 and 10 as follows:

1. (Twice amended) A metal-to-metal antifuse formed over a lower Cu metal layer planarized with the top surface of a lower insulating layer comprising:
- a metal layer disposed under said lower Cu metal layer;
  - a lower barrier layer disposed over said lower Cu metal layer;

B+C